



Material Content Data Sheet



Sales Product Name	BSS83P H6327			Issued		12. December 2019		
MA#	MA001623198							
Package	PG-SOT23-3-5			Weight*		9.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.04		404	
	noble metal	gold	7440-57-5	0.015	0.16		1566	
	inorganic material	silicon	7440-21-3	0.166	1.77	1.97	17748	19718
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	chromium	7440-47-3	0.009	0.10		967	
	non noble metal	copper	7440-50-8	3.000	32.10	32.24	321035	322389
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	772	772
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6107	
	plastics	epoxy resin	-	1.227	13.13		131295	
	inorganic material	silicondioxide	60676-86-0	4.423	47.33	61.07	473276	610678
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	16011	16011
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30432	30432
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com